



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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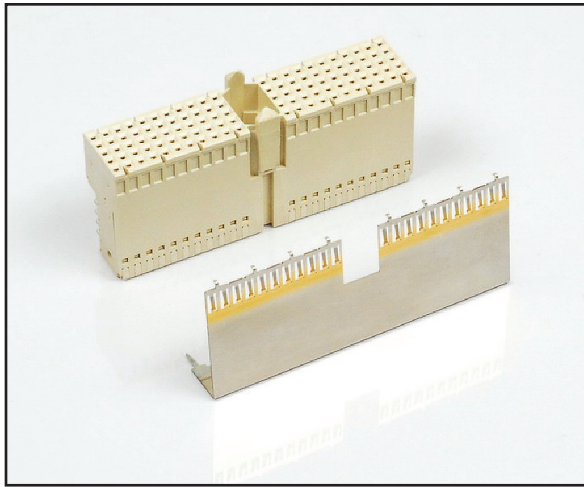
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



3M™ CP2 Press-Fit Socket

2 mm Type A 110 Signal Contacts Right Angle

CP2 Series



- 25mm basic system unit
- 50mm module
- Designed according to IEC 61076-4-101 and IEC 60352-5 Standards
- 2 mm grid spacing allows for high signal density at low cost
- “Eye of the Needle” compliant pin press-fit design reduces manufacturing time and cost
- Additional grounding row available for improved ground bounce and EMI immunity
- Mates with 5 row 3M™ MetPak™ HM, and CP2 headers
- End-to-end stackable with 5 row 3M™ MetPak™ HSHM, HM, and CP2 sockets
- See Regulatory Information Appendix (RIA) for chemical compliance information

Date Modified: February 15, 2008

TS-2266-A
Sheet 1 of 2

Physical

Insulation:

Material: High Temperature Thermoplastic (LCP)

Flammability: UL94V-0

Contact:

Material: Copper Alloy

Plating: See Ordering Information

Mechanical

Mating Force: $\leq 0.75\text{N/PIN}$

Withdrawl Force: $\geq 0.15\text{N/PIN}$

Mating and Un-mating Operations: 50

Electrical

Contact Resistance: $\leq 20\text{ m}\Omega$

Insulation Resistance: $\geq 10,000\text{ M}\Omega$

Test Voltage: $750\text{ VAC}_{\text{RMS}}$

Environmental

Temperature Ratings: -55°C to $+125^{\circ}\text{C}$

PCB Data

Recommended PCB Plated Through Hole: $\Phi 0.6\pm 0.05\text{ mm}$

Drill Hole Diameter: $\Phi 0.7\pm 0.02\text{ mm}$

Hole platings: Cu 25~50 μm , Sn or SnPb < 10 μm

PCB thickness: 1.4-4.2 mm

Press-In Force: $\leq 204\text{N/pin}$ on nominal hole diameter

Retention Force: $\geq 13.5\text{N/pin}$ on nominal hole diameter

3M

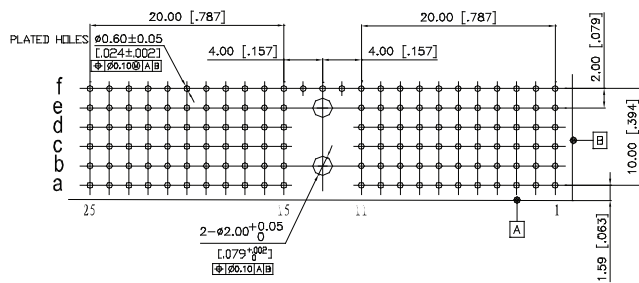
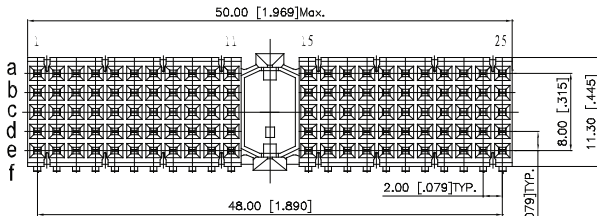
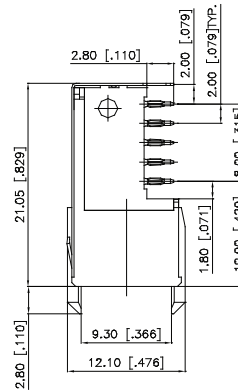
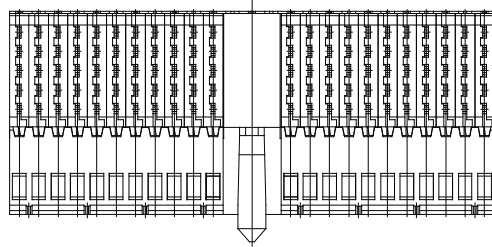
Electronic Solutions Division
Interconnect Solutions
<http://www.3M.com/interconnects/>

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800-225-5373

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2 mm Type A 110 Signal Contacts Right Angle

CP2 Series



Recommended PCB Layout

Tolerance Unless Noted			
	mm [Inch]		
	0.	.0	.00
mm	1	0.3	0.13

[] Dimensions for Reference only

Ordering Information

CP2-SA110-X1-XXXX

Shield Options
 G= Upper Shield
 Blank= No Shield

Plating Options

- TG30= 30~40 μm Gold Contact Area
 100~200 μm Bright Tin-Lead
 50~80 μm Nickel Underplate
 (RIA E2 & C2 apply)
- FJ= 10~20 μm Gold Contact Area
 200~300 μm Matte Tin
 50~80 μm Nickel Underplate
 (RIA E1 & C1 apply)
- KR= 30~40 μm Gold Contact Area
 200~300 μm Matte Tin
 50~80 μm Nickel Underplate
 (RIA E1 & C1 apply)

• This diagram serves only for Part Number descriptive definitions.

PLEASE CONTACT YOUR LOCAL SALES REPRESENTATIVE FOR CUSTOMER SPECIFIC PRODUCT CONFIGURATIONS.

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